



Material Content Data Sheet



Sales Product Name		SS07N70		Issued		27. September 2017		
MA#		MA001368816						
Package		PG-TO251-3-342		Weight*		318.41 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.509	0.79	0.79	7880	7880
leadframe	non noble metal	iron	7439-89-6	0.147	0.05		463	
	inorganic material	phosphorus	7723-14-0	0.044	0.01		139	
	non noble metal	copper	7440-50-8	147.096	46.19	46.25	461966	462568
wire	non noble metal	aluminium	7429-90-5	0.481	0.15	0.15	1509	1509
encapsulation	organic material	carbon black	1333-86-4	1.412	0.44		4435	
	plastics	epoxy resin	-	24.711	7.76		77605	
	inorganic material	silicondioxide	60676-86-0	115.081	36.14	44.34	361419	443459
leadfinish	non noble metal	tin	7440-31-5	3.787	1.19	1.19	11893	11893
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11	
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4461	4472
solder	noble metal	silver	7440-22-4	0.063	0.02		198	
	non noble metal	tin	7440-31-5	0.050	0.02		158	
	non noble metal	lead	7439-92-1	2.406	0.76	0.80	7557	7913
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		60	
	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	copper	7440-50-8	19.177	6.02	6.03	60228	60306
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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